



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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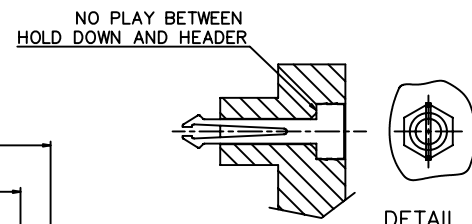
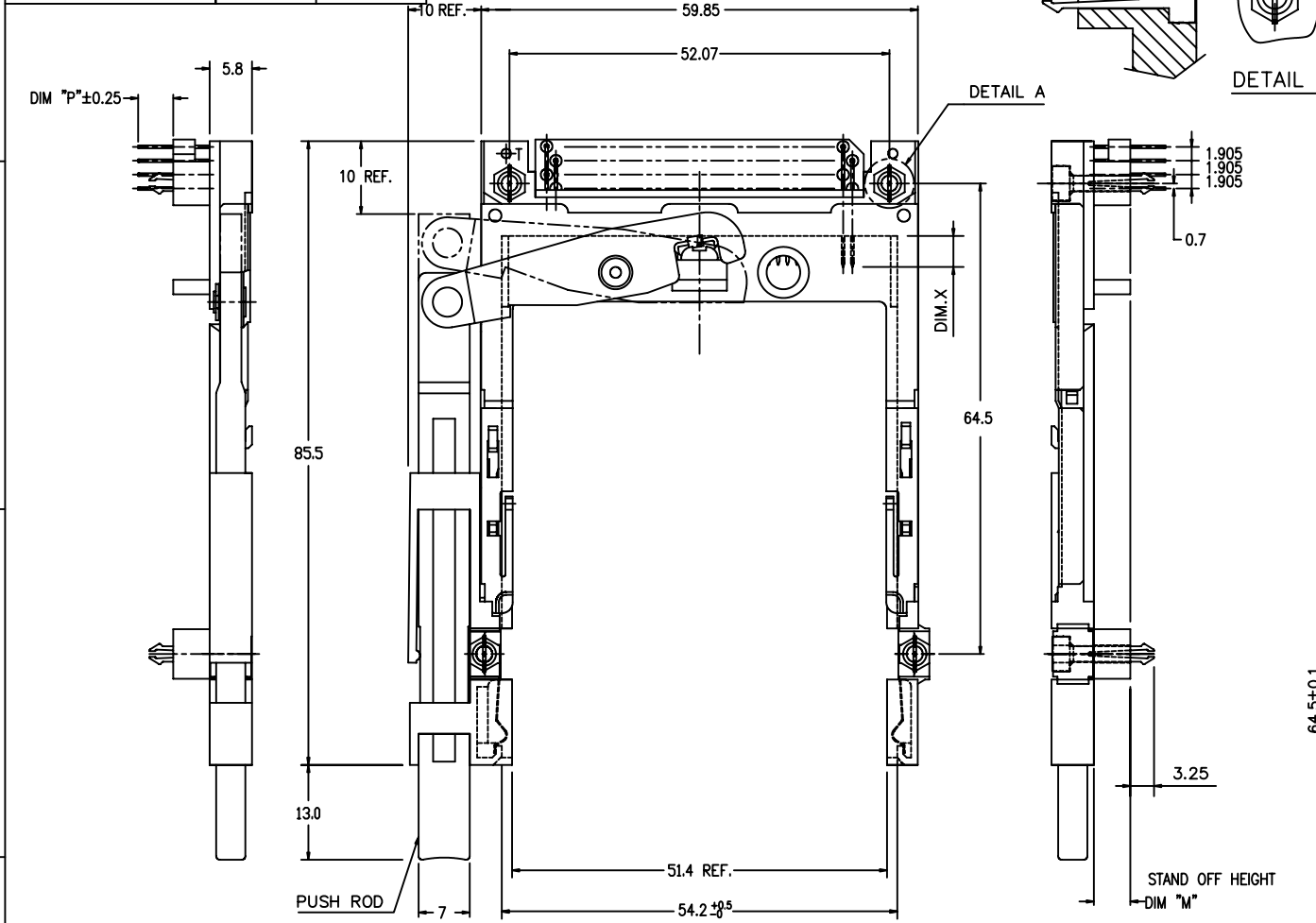
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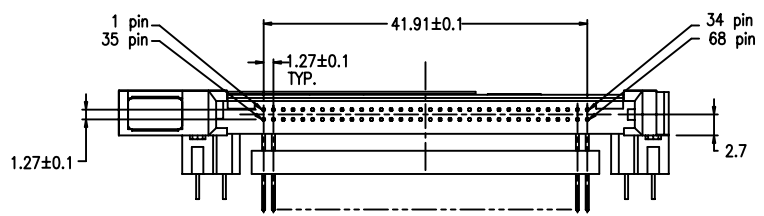
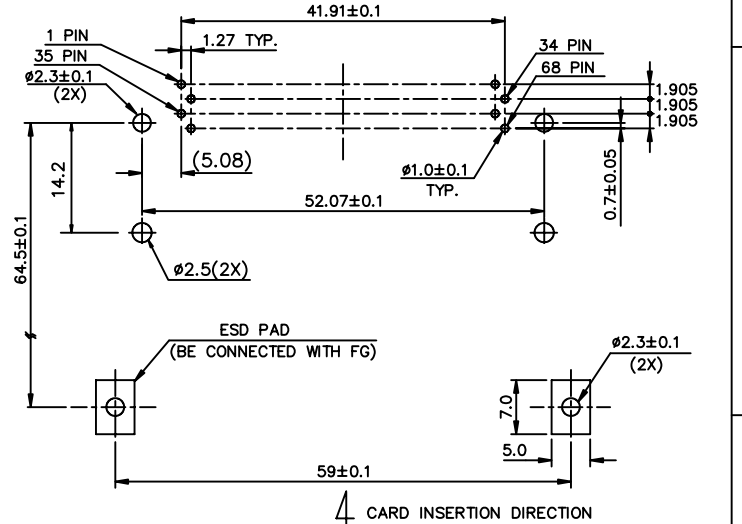
PRODUCT NO.	DIM "M"	DIM "P"
52581-130CAH	3	4.8
52581-150CAH	5	4.8
52581-130CAHLF	3	4.8
52581-150CAHLF	5	4.8



- NOTES:
- MATERIAL
 - HEADER ASS'Y:
 - PLASTIC : HOUSING ...LCP UL94V-0 BLACK
 - PIN : COPPER ALLOY
 - EJECT MECHANISM ASS'Y:
 - PLASTIC : GUIDE: POLYPHTHAMID, BLACK
 - : PUSH ROD: POLYPHTHAMID, BLACK
 - PLATE : STAINLESS
 - EMI CONTACT: PHOSPHOR BRONZE
 - FINISH (PIN)
 - UNDER PLATING : 0.5 um MIN. Ni
 - CONTACT AREA : 0.1 um MIN. GOLD OVER
 - : 0.5 um MIN. Pd-Ni
 - SOLDER TAIL : 2.5 um MIN. Sn-Pb
 - : 2.5 um MIN. PURE Sn (FOR -*****LF)

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68	

- RETENTION FORCE HOLD DOWN VERSUS HEADER: 15N MIN.
- P.C.B. THICKNESS 1.6mm.
- IF LEAD FREE P/N THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com		
rev.	ecn no.	dr	date	linear	±0.30	projection	title	
A	T00288	W L	09/21/00				SINGLE DECK,R/A EJECTOR	
B	T03-0326	W L	08/14/03				TYPE I/II/III	
C	N05-0135	W B	05/27/05	angles	± 2°			
		dr	WENDY CHEN	01/19/00	unit		product family	
		enr	LEIF SHEN	01/19/00	mm/inch		PM01A	
		chr	JOSEPH HSIAO	01/19/00	scale		code	
		appd	LELAND WANG	01/19/00	1:1	A3	52581	
sheet	revision							sheet
index	sheet							1 of 1